

REMARKS

Claims 94-99 are canceled. Claim 22 is amended. New claims 101-112 are added. No new matter is added as the originally-filed application supports the new claims at, for example, pages 10-11. Claims 22-34, 92, 93, and 100-112 remain in the application. Reconsideration of the application in view of the amendments and the remarks to follow is requested.

Claims 22, 31-32, and 100 stand rejected under 35 U.S.C. §102(b) as being anticipated by Huddleston (5,067,695). Claims 33-34 and 92-93 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Huddleston.

Regarding the anticipation rejection against claim 22, such claim is amended to recite a panel is immobile relative a plurality of blocks. No new matter is added as the originally-filed disclosure supports such amendment language at, for example, page 11. Huddleston fails to teach or suggest a panel is **immobile** relative a block as recited in claim 22. Since Huddleston fails to teach or suggest a positively recited limitation of claim 22, claim 22 is allowable.

Claims 31-34, 92-93, and 100-109 depend from independent claim 22, and therefore, are allowable for the reasons discussed above with respect to the independent claim, as well as for their own recited features which are not shown or taught by the art of record.

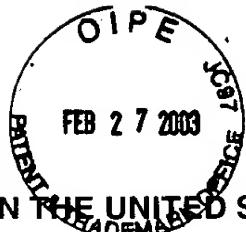
In view of the foregoing, allowance of all pending claims is requested. This application is now believed to be in immediate condition for allowance, and action to that end is respectfully requested. If the Examiner's next anticipated

action is to be anything other than a Notice of Allowance, the undersigned respectfully requests a telephone interview prior to issuance of any such subsequent action.

Respectfully submitted,

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/687,600
Filing Date October 12, 2000
Inventor Jason E. Tripard
Assignee Micron Technology, Inc.
Group Art Unit 3724
Examiner S. Choi
Attorney's Docket No. MI22-1550
Title: Integrated Circuit Package Separators

**VERSION WITH MARKINGS TO SHOW CHANGES MADE
ACCOMPANYING RESPONSE TO OCTOBER 4, 2002 OFFICE ACTION**

The replacement specification paragraphs incorporate the following amendments. Underlines indicate insertions and ~~strikeouts~~ indicate deletions.

In the Specification

On page 1, the paragraph inserted before the "Technical Field" by the amendment dated October 12, 2000, has been amended as shown below:

RELATED PATENT DATA

This patent resulted from a divisional application of United States Patent Application Serial No. 09/533,058, filed March 22, 2000, and titled "Integrated Circuit Package Separators", which is a divisional application of United States Patent Application Serial No. 09/176,479, which was filed on October 20, 1998, now U.S. Patent No. 6,277,671, the disclosures of which are incorporated by reference.

In the Claims

The claims have been amended as follows. Underlines indicate insertions and ~~strikeouts~~ indicate deletions.

22. (Amended) An integrated circuit package separator for separating a plurality of integrated circuit packages from one another, the integrated circuit packages being provided as integrated circuit chip components joined to a board, the separating including cutting the board, the separator comprising:

a panel;

a plurality of blocks over the panel, the blocks having curved upper surfaces and being configured to support the board while leaving the integrated circuit chip components extending between the block upper surfaces and the panel; and

a cutting mechanism configured to cut the board while the board is supported on the blocks and to thereby separate the integrated circuit packages from one another; and

wherein the panel is immobile relative the plurality of the blocks.

END OF DOCUMENT